

3. (Amended) The [mount] mounting method as claimed in claim 1, wherein [the] said liquid is inactive to said device and said substrate.

4. (Amended) The [mount] mounting method as claimed in claim 1, wherein said device is an optical device.

5. (Amended) The [mount] mounting method as claimed in claim 1, wherein said device is a semiconductor device.

6. (Amended) The [mount] mounting method as claimed in claim 1, wherein said substrate is a semiconductor substrate.

7. (Amended) The [mount] mounting method as claimed in claim 1, wherein said substrate is a substrate for mounting an electric element.

8. (Amended) The [mount] mounting method as claimed in claim 1, wherein said substrate is a ceramic substrate.

9. (Amended) The [mount] mounting method as claimed in claim 1, wherein said substrate is a printed circuit board.

B/C 7  
10. (Amended) A method of joining a substrate electrode formed on a substrate and a device electrode formed on a device to each other by solder to mount [the] said device on [the] said substrate, comprising the steps of:

attaching a solder piece to [the] said substrate electrode;

5 melting [the] said solder piece while said solder piece is at least partially submerged in a liquid to form a solder bump having an adhered surface and an opposite surface;  
[matching the substrate electrode having the solder bump formed thereon with the device electrode and disposing the]

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10 pre-positioning said device so as to contact said opposite surface of said solder bump [confront the substrate] while said device is at least partially submerged in [the] said liquid;

positioning [the] said device electrode to [the] said substrate electrode by surface tension of [the melted] said solder bump when [the] said solder bump is melted and while said device is at least partially submerged in [the] said liquid and at least partially supported by a  
.5 buoyant force [to join the] thereby joining said device electrode and [the] said substrate electrode to each other; and then

solidifying [the] said solder bump.

2 X 11. (Amended) The method as claimed in claim 10, wherein as [when the] said solder piece is melted to form [the] said solder bump, [ultrasonic] a vibration is applied to [the] said solder piece [through the] while said solder piece is at least partially submerged in said liquid.

3 ~~12~~ (Amended) The method as claimed in claim ~~10~~, wherein when [the] said solder bump is melted while said solder bump is at least partially submerged in [the] said liquid to join [the] said device electrode and [the] said substrate electrode to each other, [ultrasonic] a vibration is applied to [the] said solder bump [through the] while said device is at least partially submerged in said liquid.

4 ~~13~~ (Amended) The method as claimed in claim ~~10~~, wherein [the] said liquid is inactive to said solder, said device and said substrate.

Please add the following new claims:

AC B/c ~~19~~ 20. The method as claimed in claim ~~2~~, wherein said vibration is applied ultrasonically.

11 ~~21~~ 2 The method as claimed in claim ~~11~~, wherein said vibration is applied ultrasonically.

12 ~~22~~ 3 The method as claimed in claim ~~12~~, wherein said vibration is applied ultrasonically.

AC B/c 23. The method as claimed in claim 1, wherein the joining of said device to said substrate is performed while a vibration is applied ultrasonically through said liquid to said solder disposed in said liquid.